



# SPN6242

## N-Channel Enhancement Mode MOSFET

### DESCRIPTION

The SPN6242 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

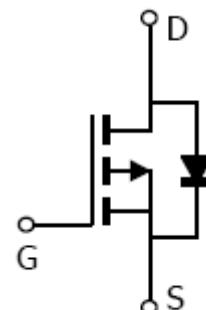
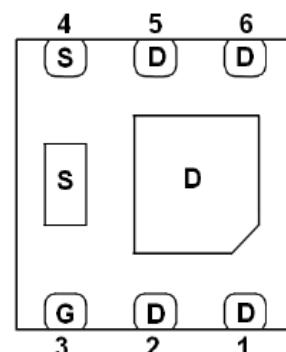
### FEATURES

- ◆ 20V/3.3A,R<sub>DS(ON)</sub>=19mΩ@V<sub>GS</sub>=4.5V
- ◆ 20V/2.8A,R<sub>DS(ON)</sub>=24mΩ@V<sub>GS</sub>=2.5V
- ◆ 20V/2.3A,R<sub>DS(ON)</sub>=32mΩ@V<sub>GS</sub>=1.8V
- ◆ Super high density cell design for extremely low R<sub>DS</sub> (ON)
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ UDFN2x2-6L package design

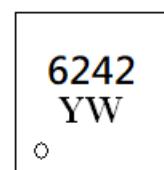
### APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

### PIN CONFIGURATION(UDFN2x2-6L)



### PART MARKING



Y : Year Code  
W: Week Code



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### PIN DESCRIPTION

Pin	Symbol	Description
1	D	Drain
2	D	Drain
3	G	Gate
4	S	Source
5	D	Drain
6	D	Drain

### ORDERING INFORMATION

Part Number	Package	Part Marking
SPN6242UDN6RGB	UDFN2x2-6L	6242YW

※ Week Code : A ~ Z( 1 ~ 26 ) ; a ~ z( 27 ~ 52 )

※ SPN6242UDN6RGB : Tape Reel ; Pb – Free ; Halogen – Free

### ABSOLUT MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	20	V
Gate –Source Voltage	V <sub>GSS</sub>	±10	V
Continuous Drain Current(T <sub>J</sub> =150°C)	T <sub>C</sub> =25°C	ID	A
	T <sub>C</sub> =100°C		
Pulsed Drain Current (*1)	I <sub>DM</sub>	26.8	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	6.7	A
Power Dissipation	T <sub>A</sub> =25°C	P <sub>D</sub>	W
	T <sub>A</sub> =70°C		
Operating Junction Temperature	T <sub>J</sub>	-55/150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	65	°C/W



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ELECTRICAL CHARACTERISTICS (TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, ID=250uA	20			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , ID=250uA	0.3	0.6	0.8	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±10V			±100	nA
Zero Gate Voltage Drain Current	ID <sub>S</sub>	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, TJ=25°C			1	uA
		V <sub>DS</sub> =16V, V <sub>GS</sub> =0V TJ=125°C			10	
Drain-Source On-Resistance	R <sub>D(on)</sub>	V <sub>GS</sub> =4.5V, ID=3.3A		15	19	mΩ
		V <sub>GS</sub> =2.5V, ID=2.8A		18	24	
		V <sub>GS</sub> =1.8V, ID=2.3A		23	32	
Forward Transconductance	g <sub>f</sub>	V <sub>DS</sub> =10V, ID=4A		9.5		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =1A, V <sub>GS</sub> =0V, TJ=25°C			1	V
<b>Dynamic</b>						
Total Gate Charge (*2,3)	Q <sub>g</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V ID=4A		5.8	8	nC
Gate-Source Charge (*2,3)	Q <sub>gs</sub>			0.6	1	
Gate-Drain Charge (*2,3)	Q <sub>gd</sub>			2	4	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V f=1MHz		600	870	pF
Output Capacitance	C <sub>oss</sub>			70	100	
Reverse Transfer Capacitance	C <sub>rss</sub>			45	65	
Turn-On Time (*2,3)	td(on)	V <sub>DD</sub> =10V, ID=1A, V <sub>GEN</sub> =4.5V RG=25Ω		5.0	9	nS
	tr			14.4	27	
Turn-Off Time (*2,3)	td(off)			30	55	
	tf			9.2	17	

Note :

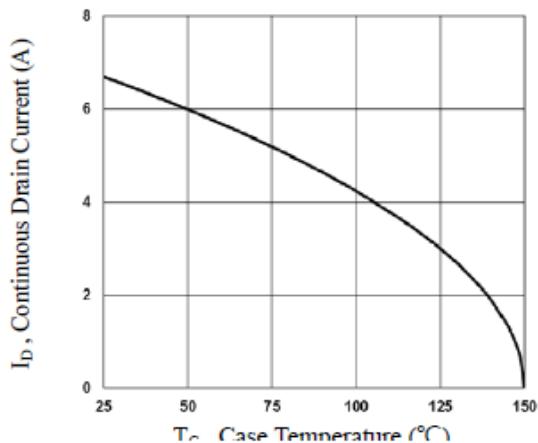
- 1.Repetitive Rating : Pulsed width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%.
- 3.Essentially independent of operating temperature.



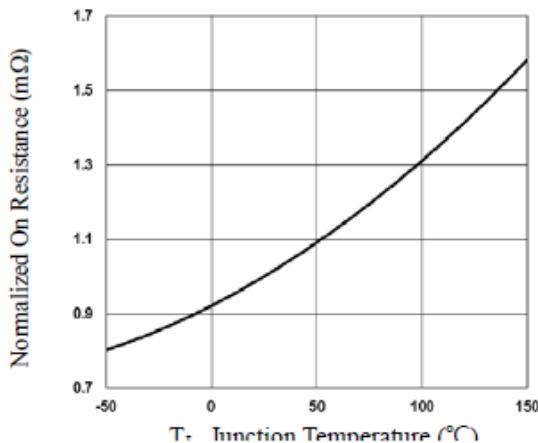
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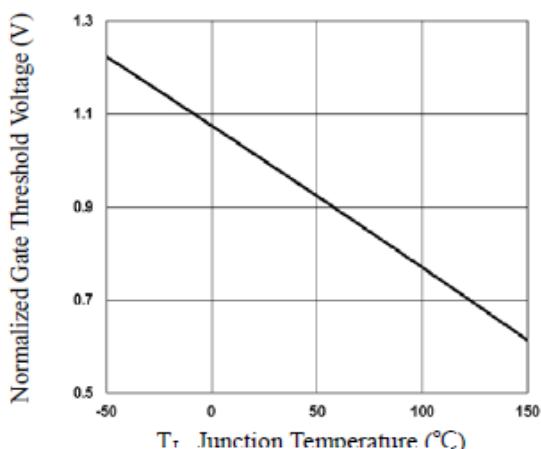
### TYPICAL CHARACTERISTICS



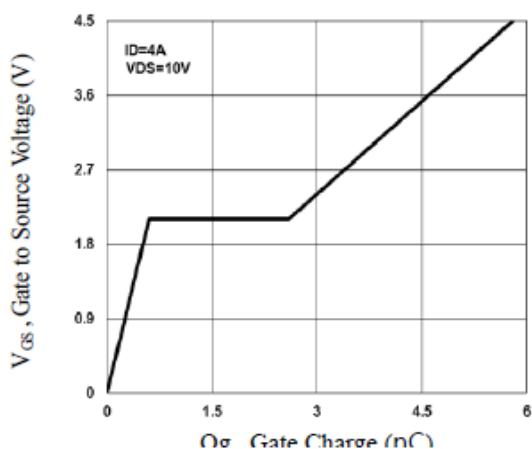
**Fig.1** Continuous Drain Current vs.  $T_C$



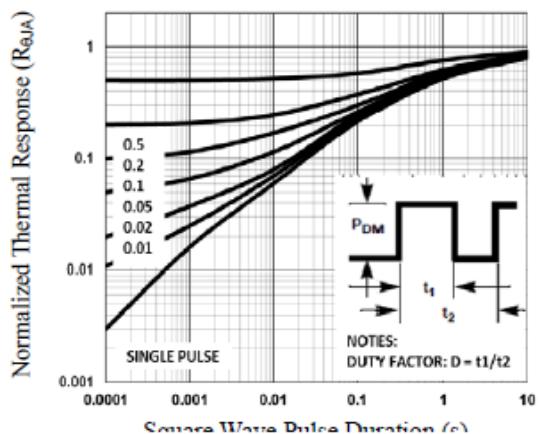
**Fig.2** Normalized RD<sub>SON</sub> vs.  $T_J$



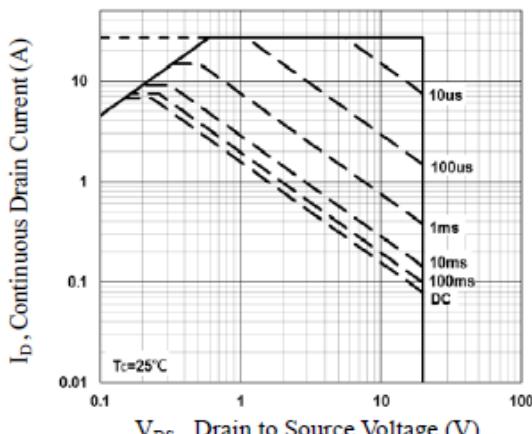
**Fig.3** Normalized  $V_{th}$  vs.  $T_J$



**Fig.4** Gate Charge Waveform



**Fig.5** Normalized Transient Impedance



**Fig.6** Maximum Safe Operation Area



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### TYPICAL CHARACTERISTICS

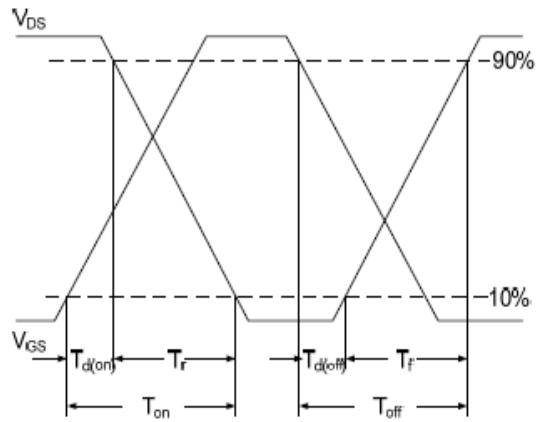


Fig.7 Switching Time Waveform

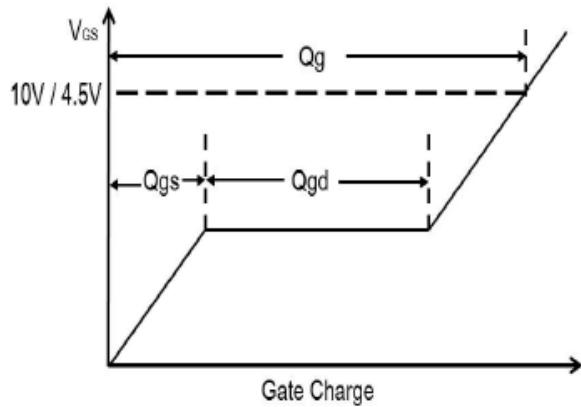


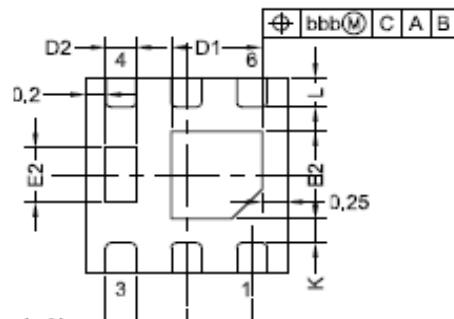
Fig.8 Gate Charge Waveform



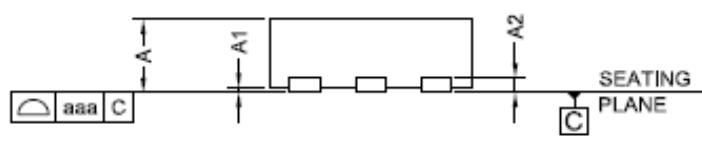
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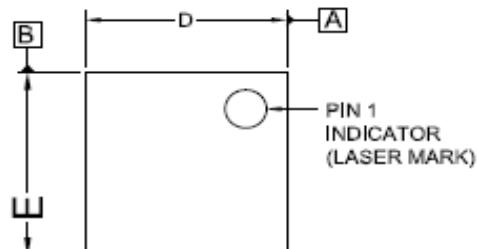
### UDFN2X2-6L PACKAGE OUTLINE



BOTTOM VIEW



SIDE VIEW



TOP VIEW

SYMBOL	MIN	TYP	MAX
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A2	0.152REF.		
b	0.25	0.30	0.35
D	1.95	2.00	2.05
D1	0.80	0.90	1.00
D2	0.25	0.30	0.35
E	1.95	2.00	2.05
E1	0.80	0.90	1.00
E2	0.46	0.56	0.66
g	0.65BSC		
L	0.25	0.30	0.35
J	0.40BSC		
K	0.20MIN		
N	6		
aaa	0.08		
bbb	0.10		



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